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TITLE : EPOXY RESIN COMPOSITION AND RESIN-SEALED TYPE SEMICONDUCTOR
DEVICE

ABSTRACT : PROBLEM TO BE SOLVED: To obtain an epoxy resin composition for semiconductor sealing, having excellent flame retardance and reliability of moisture resistance without using a halogen-based flame retardant or an antimony-based flame retardant and to provide a resin-sealed semiconductor device.

SOLUTION: This resin composition comprises (A) an epoxy resin, (B) a curing agent, (C) a curing promoter, (D) an inorganic filler, (E) a particle obtained by coating the surface of red phosphorus with at least one kind of aluminum hydroxide and a phenol resin, (F) a nitrogen atom-containing compound, (G) an inorganic compound containing at least one kind of a first group consisting of low-melting glass powder, zinc stannate, zinc hydroxystannate, zinc molybdate and molybdenum trioxide.

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